

IEC SYSTEM FOR MUTUAL RECOGNITION OF TEST CERTIFICATES FOR ELECTRICAL EQUIPMENT (IECEE)
CB SCHEME

CB TEST CERTIFICATE

Product

1) Intel® NUC Rugged Chassis Element (Docking)
2) Intel® NUC Pro Chassis Element (Docking)

Name and address of the applicant

INTEL CORPORATION
2200 MISSION COLLEGE BLVD SANTA CLARA, CA
95054-1537 USA

Name and address of the manufacturer

INTEL CORPORATION
2200 MISSION COLLEGE BLVD SANTA CLARA, CA
95054-1537 USA

Name and address of the factory

GOLDEN ELITE TECHNOLOGY (SHEN ZHEN) LTD
1 NAN HUAN RD SHAJING BAO AN SHENZHEN GUANGDONG
518104
CHINA*Note: When more than one factory, please report on page 2* Additional Information on page 2

Ratings and principal characteristics

19 Vdc., 4.74 A

Trademark / Brand (if any)



Type of Customer's Testing Facility (CTF) Stage used

Model / Type Ref.

1) xCMCR1ABx, 2) xCMCM2FBx
(where x can be a combination of alphanumeric characters,
none or blank)Additional information (if necessary may also be
reported on page 2) Additional Information on page 2A sample of the product was tested and found
to be in conformity with

IEC 62368-1:2014

As shown in the Test Report Ref. No. which forms part
of this Certificate

ATTCB108120-02 issued on 2020-07-08

This CB Test Certificate is issued by the National Certification Body



- UL (US), 333 Pfingsten Rd IL 60062, Northbrook, USA
- UL (Demko), Borupvang 5A DK-2750 Ballerup, DENMARK
- UL (JP), Marunouchi Trust Tower Main Building 6F, 1-8-3 Marunouchi, Chiyoda-ku, Tokyo 100-0005, JAPAN
- UL (CA), 7 Underwriters Road, Toronto, M1R 3B4 Ontario, CANADA

For full legal entity names see www.ul.com/ncbnames

Date: 2020-07-10

Signature:

Original Issue Date: 2019-10-18

Jan-Erik Storgaard



Ref. Certif. No.

DK-88652-A1-UL

Additional Information:

Additionally evaluated to EN 62368-1:2014/A11:2017

National Difference specified in the CB Test Report

Reason for Correction:

-Correct amendment information due to typo, see below for details:

Add new construction for new model name: xCMCM2FBx with xCM8xCBx (type A, type B, type C) and xCMB1ABx (type B) as below:

- Add product name: Intel® NUC Pro Chassis Element (Docking)
- Add thermal pad (type D)
- Add ambient (35 °C)
- Add enclosure chassis (type B)
- Add heatsink (type B) with DC Fan.
- Add VESA mount (type B) (optional)
- Add daughter board (optional)

Additional information (if necessary)



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